

Title (en)
ADDITIVE FOR MOLDING OF CERAMIC MATERIAL

Title (de)
ADDITIVE ZUM FORMEN EINES KERAMIKMATERIALS

Title (fr)
ADDITIF POUR LE MOULAGE DE MATÉRIAU CÉRAMIQUE

Publication
EP 2615074 B1 20190320 (EN)

Application
EP 11823553 A 20110906

Priority

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- JP 2011070227 W 20110906

Abstract (en)
[origin: EP2615074A1] The present invention relates to an additive for use in the molding of a ceramic material, which exhibits satisfactory water absorption performance in a ceramic green ceramic clay, can highly achieve both high fluidability and low loading performance during extrusion molding and high shape-retaining performance after extrusion at the same time, and comprises polymer microparticles. This additive for use in the molding of a ceramic material comprises polymer microparticles, is characterized in that the polymer microparticles have an average particle size between 10 and 150 µm when the polymer microparticles are swollen with ion exchange water until the swollen polymer microparticles reach a saturated state and can absorb 10-60 mL/g of ion exchange water under ordinary pressure, and is also characterized in that an aqueous dispersion prepared by dispersing 1 part by mass of the polymer microparticles in 110 parts by mass of ion exchange water has an electrical conductivity of 1500 µS/cm or less at 25 °C.

IPC 8 full level
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C04B 24/12 (2013.01 - US); **C04B 24/124** (2013.01 - US); **C04B 35/195** (2013.01 - EP US); **C04B 35/632** (2013.01 - US); **C04B 35/634** (2013.01 - EP US); **C08F 4/40** (2013.01 - EP US); **C08F 20/06** (2013.01 - EP US); **C08F 20/58** (2013.01 - EP US); **C08F 220/06** (2013.01 - EP US); **C04B 2235/5427** (2013.01 - EP US); **C04B 2235/5436** (2013.01 - EP US); **C04B 2235/5463** (2013.01 - EP US); **C04B 2235/6021** (2013.01 - EP US); **C04B 2235/606** (2013.01 - EP US); **C04B 2235/9638** (2013.01 - EP US); **H01B 1/12** (2013.01 - US)

C-Set (source: EP US)
EP
1. **C08F 220/06 + C08F 220/56 + C08F 220/286**
2. **C08F 220/56 + C08F 220/06 + C08F 222/1063**
3. **C08F 220/585 + C08F 220/56 + C08F 222/1063**
4. **C08F 220/06 + C08F 220/56 + C08F 222/1063**
5. **C08F 220/06 + C08F 222/1063**
US
1. **C08F 220/06 + C08F 220/56 + C08F 220/286**
2. **C08F 220/06 + C08F 220/56 + C08F 222/1063**
3. **C08F 220/585 + C08F 220/56 + C08F 222/1063**
4. **C08F 220/06 + C08F 222/1063**
5. **C08F 220/56 + C08F 220/06 + C08F 222/1063**

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